Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

Claim 1 (canceled)

Claim 2 (currently amended): A lead-free solder used to connect a connection lead to a material, comprising:

an alloy composition containing 0.002 to 0.015% by mass of phosphorus with the balance consisting of ~~tin,~~ tin;

wherein said alloy composition excludes bismuth; and

wherein antimony is not intentionally added to said alloy composition.

Claim 3 (canceled)

Claim 4 (currently amended): A connection lead comprising:

a copper strip or other strip conductor; and

a plating provided on at least one side of the strip constructor, said plating being formed of a lead-free solder composed mainly of tin,

said plating containing 0.002 to 0.015% by mass of phosphorus with the balance consisting of tin and excluding bismuth, and having a shape such that the plating in a widthwise direction of the strip conductor has a bulge as viewed in section with an apex being located at a proper position in the widthwise direction of the strip conductor; and

wherein antimony is not intentionally added to said plating.

Claim 5 (original): The connection lead according to claim 4, wherein the bulge is in the form of an arc, a triangle, or stairs of which the apex is located at a proper position in the widthwise direction of the strip conductor.

Claim 6 (canceled)

Claim 7 (original): The connection lead according to claim 4, wherein the strip conductor on its both sides are exposed or are covered with the lead-free solder constituting the plating.

Claims 8-13 (canceled)

Claim 14 (previously presented): The lead free solder according to claim 2, wherein:

the alloy composition further containing 2.0 to 5.0% by mass of silver and 0.01 to 2.0% by mass of copper.

Claim 15 (currently amended): An alloy composition for a lead free solder used to connect a connection lead to a material, comprising:

0.002 to 0.015% by mass of phosphorus; and

~~tin,~~ tin;

wherein said alloy composition excludes bismuth; and

wherein antimony is not intentionally added to said alloy composition .

Claim 16 (previously presented): The alloy composition according to claim 15, wherein the tin forms the balance of the composition.

Claim 17 (previously presented): An alloy composition for a lead free solder used to connect a connection lead to a material, consisting essentially of:

0.002 to 0.015% by mass of phosphorus;

2.0 to 5.0% by mass of silver;

0.01 to 2.0% by mass of copper; and

tin.

Claim 18 (previously presented): The connection lead according to claim 4, wherein said plating further containing 2.0 to 5.0% by mass of silver and 0.01 to 2.0% by mass of copper.

Claim 19 (previously presented): The alloy composition according to claim 15, further comprising:

2.0 to 5.0% by mass of silver; and

0.01 to 2.0% by mass of copper.

Claim 20 (new): The lead-free solder according to claim 2, wherein said alloy composition excludes antimony.

Claim 21 (new): The connection lead according to claim 4, wherein said plating excludes antimony.

Claim 22 (new): The alloy composition according to claim 15, wherein said alloy composition excludes antimony.

Claim 23 (new): The alloy composition according to claim 17, wherein antimony is not intentionally added to said alloy composition.